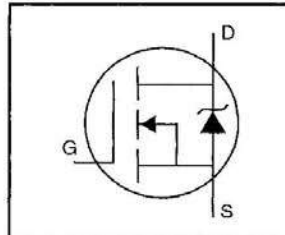


IRFPG40PbF

HEXFET® Power MOSFET

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- Isolated Central Mounting Hole
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Lead-Free



$$V_{DSS} = 1000V$$

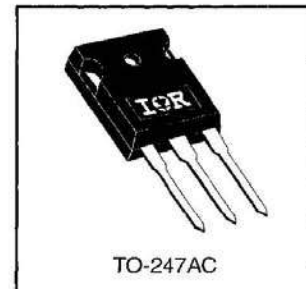
$$R_{DS(on)} = 3.5\Omega$$

$$I_D = 4.3A$$

Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-247 package is preferred for commercial-industrial applications where higher power levels preclude the use of TO-220 devices. The TO-247 is similar but superior to the earlier TO-218 package because of its isolated mounting hole. It also provides greater creepage distance between pins to meet the requirements of most safety specifications.



Absolute Maximum Ratings

	Parameter	Max.	Units
I_D @ $T_C = 25^\circ C$	Continuous Drain Current, V_{GS} @ 10 V	4.3	A
I_D @ $T_C = 100^\circ C$	Continuous Drain Current, V_{GS} @ 10 V	2.7	
I_{DM}	Pulsed Drain Current ①	17	
P_D @ $T_C = 25^\circ C$	Power Dissipation	150	W
	Linear Derating Factor	1.2	W/ $^\circ C$
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy ②	490	mJ
I_{AR}	Avalanche Current ①	4.3	A
E_{AR}	Repetitive Avalanche Energy ①	15	mJ
dv/dt	Peak Diode Recovery dv/dt ③	1.0	V/ns
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ C$
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting Torque, 6-32 or M3 screw	10 lbf•in (1.1 N•m)	

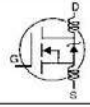
Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	—	0.83	$^\circ C/W$
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	—	0.24	—	
$R_{\theta JA}$	Junction-to-Ambient	—	—	40	

IRFPG40PbF

International
IR Rectifier

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	1000	—	—	V	$V_{GS}=0V$, $I_D=250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	1.3	—	V/ $^\circ\text{C}$	Reference to 25°C , $I_D=1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	3.5	Ω	$V_{GS}=10V$, $I_D=2.6A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS}=V_{GS}$, $I_D=250\mu A$
g_{fs}	Forward Transconductance	33	—	—	S	$V_{DS}=50V$, $I_D=2.6A$ ④
I_{DSS}	Drain-to-Source Leakage Current	—	—	100	μA	$V_{DS}=1000V$, $V_{GS}=0V$
		—	—	500		$V_{DS}=800V$, $V_{GS}=0V$, $T_J=125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS}=20V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS}=-20V$
Q_g	Total Gate Charge	—	—	120	nC	$I_D=4.3A$
Q_{gs}	Gate-to-Source Charge	—	—	16		$V_{DS}=400V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	65		$V_{GS}=10V$ See Fig. 6 and 13 ④
$t_{d(on)}$	Turn-On Delay Time	—	15	—	ns	$V_{DD}=500V$
t_r	Rise Time	—	33	—		$I_D=4.3A$
$t_{d(off)}$	Turn-Off Delay Time	—	100	—		$R_G=9.1\Omega$
t_f	Fall Time	—	30	—		$R_D=120\Omega$ See Figure 10 ④
L_D	Internal Drain Inductance	—	5.0	—	nH	Between lead, 6 mm (0.25in.) from package and center of die contact 
L_S	Internal Source Inductance	—	13	—		
C_{iss}	Input Capacitance	—	1600	—	pF	$V_{GS}=0V$
C_{oss}	Output Capacitance	—	170	—		$V_{DS}=25V$
C_{rss}	Reverse Transfer Capacitance	—	56	—		$f=1.0\text{MHz}$ See Figure 5

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I_S	Continuous Source Current (Body Diode)	—	—	4.3	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	17		
V_{SD}	Diode Forward Voltage	—	—	1.8	V	$T_J=25^\circ\text{C}$, $I_S=4.3A$, $V_{GS}=0V$ ④
t_{rr}	Reverse Recovery Time	—	470	710	ns	$T_J=25^\circ\text{C}$, $I_F=4.3A$
Q_{rr}	Reverse Recovery Charge	—	1.9	2.9	μC	$di/dt=100A/\mu s$ ④
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Notes:

① Repetitive rating; pulse width limited by max. junction temperature (See Figure 11)

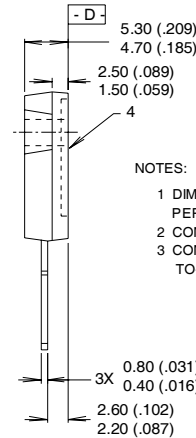
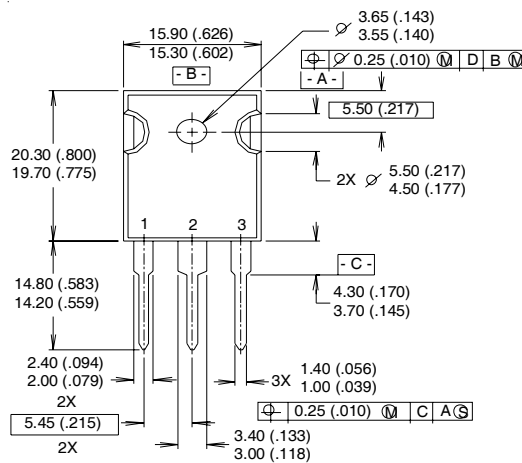
② $V_{DD}=50V$, starting $T_J=25^\circ\text{C}$, $L=50\text{mH}$, $R_G=25\Omega$, $I_{AS}=4.3A$ (See Figure 12)

③ $I_{SD}\leq 4.3A$, $di/dt\leq 100A/\mu s$, $V_{DD}\leq 600V$, $T_J\leq 150^\circ\text{C}$

④ Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.

TO-247AC Package Outline

Dimensions are shown in millimeters (inches)



NOTES:

- 1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.
- 2 CONTROLLING DIMENSION : INCH.
- 3 CONFORMS TO JEDEC OUTLINE TO-247-AC.

LEAD ASSIGNMENTS

Hexfet	IGBT
1 - Gate	1 - Gate
2 - Drain	2 - Collector
3 - Source	3 - Emitter
4 - Drain	4 - Collector

TO-247AC Part Marking Information

EXAMPLE: THIS IS AN IRFPE30
WITH ASSEMBLY
LOT CODE 5657
ASSEMBLED ON VW 35, 2000
IN THE ASSEMBLY LINE "H"
Note: "P" in assembly line
position indicates "Lead-Free"

